Advance Info

TFB0503

Half-Bridge Gate Driver

TF Semiconductor Solutions

Features

- **Floating high-side driver in bootstrap operation to 100V**
- **Drives two N-channel MOSFETs or IGBTs in a half bridge configuration**
- **Integrated bootstrap diode for compact design**
- **300mA source/550mA sink output current capability**
- **Outputs tolerant to negative transients**
- **Internal dead time of 420ns to protect MOSFETs**
- **Wide low side gate driver supply voltage: 10V to 20V**
- **Logic input (HIN and LIN*) 3.3V capability**
- **Schmitt triggered logic inputs**
- **Undervoltage lockout for V_{CC} (logic and low side supply)**
- **Extended temperature range: -40°C to +125°C**
- **Space saving TDFN-10 3x3mm package**

Description

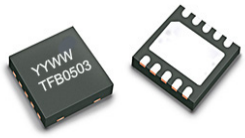
The TFB0503 is a half-bridge gate driver with integrated bootstrap diode capable of driving N-channel MOSFETs and IGBTs in a half-bridge configuration. TF Semiconductor's advanced process enables the floating high-side driver to operate to 100V in a bootstrap configuration.

The TFB0503 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. TFB0503 has a fixed internal deadtime of 420ns (typical).

To simplify design and decrease the BOM, the TFB0503 has an integrated bootstrap diode. Also the TFB0503 is offered in a space saving TDFN-10 package and operates over an extended -40 °C to +125 °C temperature range.

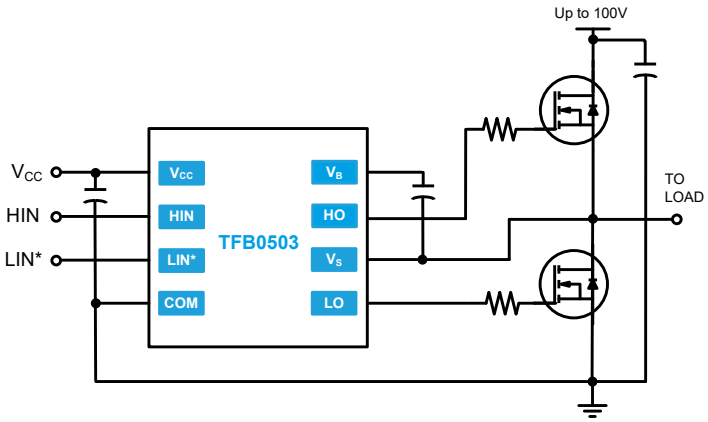
Applications

- Stepper motor drives
- DC-DC Converters
- Battery powered tools
- BLDC motor drive



TDFN-10

Typical Application

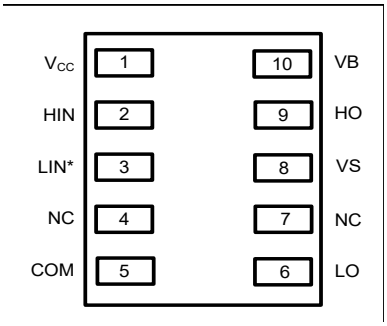


Year Year Week Week

Ordering Information

PART NUMBER	PACKAGE	PACK / Qty	MARK
TFB0503-NHS	TDFN-10	Tube / 120	YYWW TFB0503
TFB0503-NHP	TDFN-10	T&R / 3,000	

Pin Diagrams

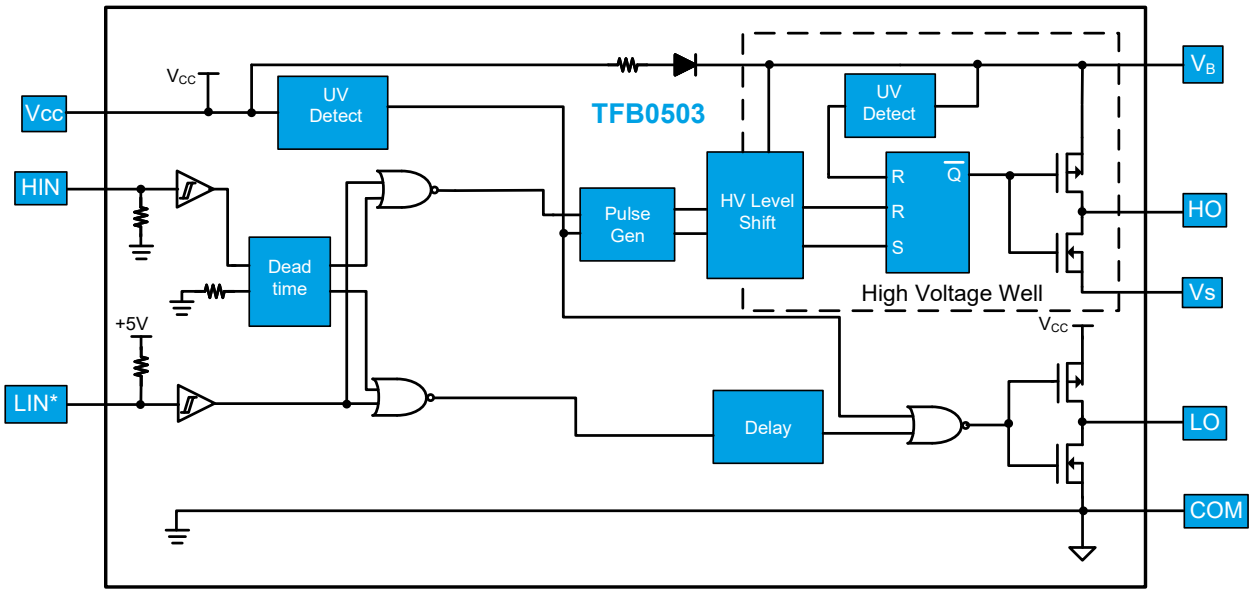


Top View: TDFN-10

Pin Descriptions

PIN NAME	PIN NUMBER	PIN DESCRIPTION
V_{CC}	1	Logic and low side supply
HIN	2	Logic input for high-side gate driver output in phase with HO
LIN*	3	Logic input for low-side gate driver output out of phase with LO
NC	4, 7	No connect
COM	5	Low-side and logic return
LO	6	Low-side gate drive output
V_S	8	High-side floating supply return
HO	9	High-side gate drive output
V_B	10	High-side floating supply

Functional Block Diagram



Absolute Maximum Ratings *(NOTE1)*

V_B - High side floating supply voltage.....-0.3V to +124V
V_S - High side floating supply offset voltage....V_B-24V to V_B+0.3V
V_{HO} - High side floating output voltage.....V_S-0.3V to V_B+0.3V
dV_S/dt - Offset supply voltage transient.....50 V/ns

V_{CC} - Low-side fixed supply voltage.....-0.3V to +24V
V_{LO} - Low-side output voltage.....-0.3V to V_{CC} +0.3V
V_{IN} - Logic input voltage (HIN and LIN*).....-0.3V to V_{CC} +0.3V

NOTE1 *Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

P_D - Package power dissipation at $T_A \leq 25$ °C
TDFN-10.....0.4W

TDFN-10 Thermal Resistance ***(NOTE2)***
θ_{JA}.....64°C/W
θ_{JC}.....42°C/W

T_J - Junction operating temperature.....+150 °C
T_L - Lead Temperature (soldering, 10 seconds).....+300 °C
T_{stg} - Storage temerature .....-55 to 150 °C

NOTE2 *When mounted on a standard JEDEC 2-layer FR-4 board.*

Recommended Operating Conditions

Symbol	Parameter	MIN	MAX	Unit
V_B	High side floating supply absolute voltage	V_S + 10	V_S + 20	V
V_S	High side floating supply offset voltage	***NOTE3***	100	V
V_{HO}	High side floating output voltage	V_S	V_B	V
V_{CC}	Low side fixed supply voltage	10	20	V
V_{LO}	Low side output voltage	0	V_{CC}	V
V_{IN}	Logic input voltage (HIN and LIN*)	0	5	V
T_A	Ambient temperature	-40	125	°C

NOTE3 *Logic operational for VS of -5V to +100V.*

DC Electrical Characteristics *(NOTE4)*

V_{BIAS} (V_{CC}, V_{BS}) = 15V, T_A = 25 °C , unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
V_{IH}	Logic "1" (HIN) & Logic "0" (LIN*) input voltage	V_{CC} = 10V to 20V *NOTE5*	2.5			V
V_{IL}	Logic "0" (HIN) & Logic "1" (LIN*) input voltage				0.8	
V_{OH}	High level output voltage, V_{BIAS} - V_O	I_O = 2mA		0.05	0.2	
V_{OL}	Low level output voltage, V_O	I_O = 2mA		0.02	0.1	
I_{LK}	Offset supply leakage current	VB = VS = 100V			50	µA
I_{BSQ}	Quiescent V_{BS} supply current	V_{IN} = 0V or 5V		7	50	
I_{CCQ}	Quiescent V_{CC} supply current	V_{IN} = 0V or 5V		350	500	
I_{IN+}	Logic "1" input bias current	HIN = 5V, LIN* = 0V		3	10	
I_{IN-}	Logic "0" input bias current	HIN = 0V, LIN* = 5V			5	
V_{CCUV+}	V_{CC} supply under-voltage positive going threshold		7.0	8.4	9.8	V
V_{CCUV-}	V_{CC} supply under-voltage negative going threshold		6.5	7.8	9.3	
V_{BSUV+}	V_{BS} supply under-voltage positive going threshold			4.5		V
V_{BSUV-}	V_{BS} supply under-voltage negative going threshold			3.7		V
I_{O+}	Output high short circuit pulsed current	V_O = 0V, PW ≤ 10 µs	130	300		mA
I_{O-}	Output low short circuit pulsed current	V_O = 15V, PW ≤ 10 µs	270	550		

NOTE4 *The V_{IN}, V_{TH}, and I_{IN} parameters are applicable to the two logic input pins: HIN and LIN*. The V_0 and I_0 parameters are applicable to the respective output pins: HO and LO.*

NOTE5 *For optimal operation, it is recommended that the input pulse (to HIN and LIN*) should have an amplitude of 2.5V minimum with a pulse width of 840ns minimum.*

AC Electrical Characteristics

V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, and T_A = 25 °C , unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
t_{on}	Turn-on propagation delay	V_S = 0V		560	820	ns
t_{off}	Turn-off propagation delay	V_S = 600V		150	220	
t_{DM}	Delay matching, HS & LS turn-on/turn-off				70	
t_r	Turn-on rise time	V_S = 0V		80	170	
t_f	Turn-off fall time			35	90	
t_{DT}	Deadtime: $t_{DT\ LO\text{-}HO}$ & $t_{DT\ HO\text{-}LO}$		300	420	650	

Application Information

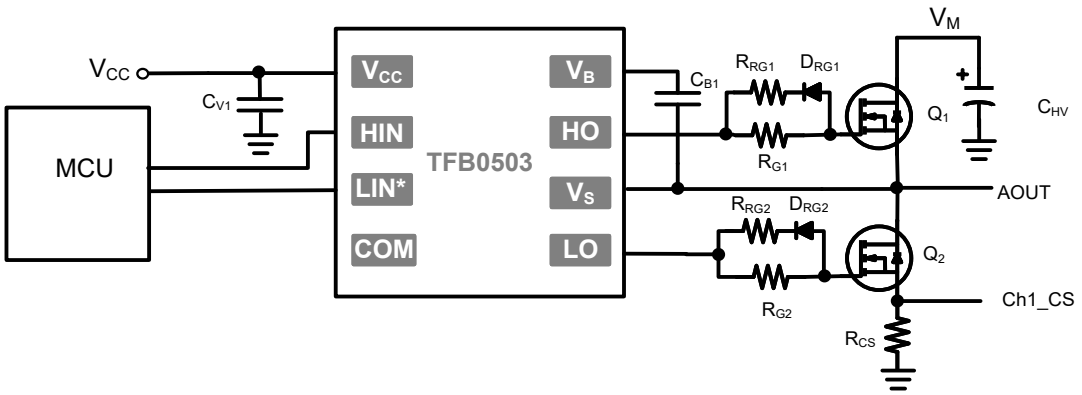


Figure 6. Single phase (of four) for Stepper motor driver application using the TF0503

- RRG1 and RRG2 values are typically between 0Ω and 10Ω, exact value decided by MOSFET junction capacitance and drive current of gate driver; 10Ω is used in this example.

- RG1 and RG2 values are typically between 20Ω and 100Ω, exact value decided by MOSFET junction capacitance and drive current of gate driver; 50Ω is used in this example.

- RB1 value is typically between 3Ω and 20Ω, exact value depending on bootstrap capacitor value and amount of current limiting required for bootstrap capacitor charging; 10Ω is used in this example. Also DB should be an ultra fast diode of 1A rating minimum and voltage rating greater than system operating voltage.

- It is recommended that the input pulse (to HIN and LIN*) should have an amplitude of 2.5V minimum (for VDD=15V) with a minimum pulse width of 840ns.

Timing Waveforms

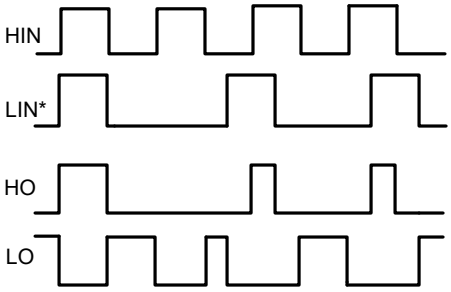


Figure 1. Input / Output Timing Diagram

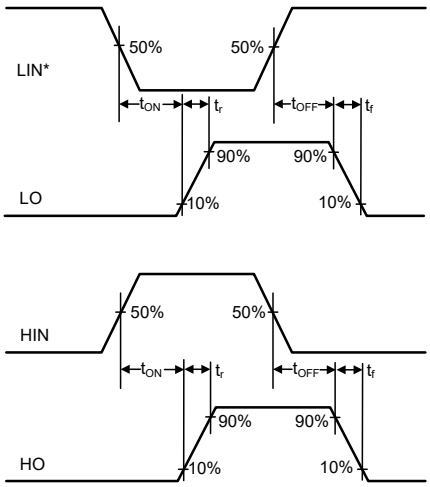


Figure 2. Switching Time Waveform Definitions

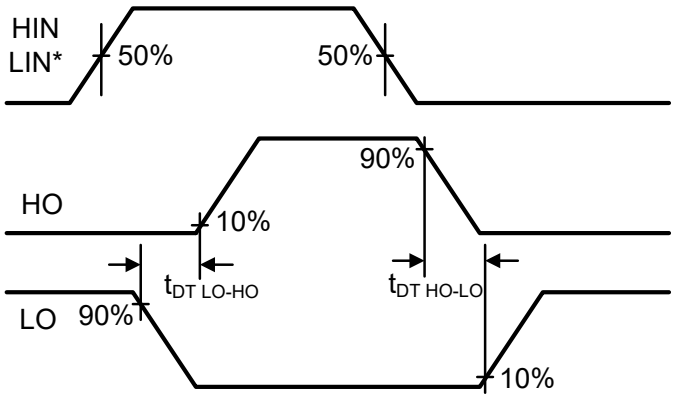
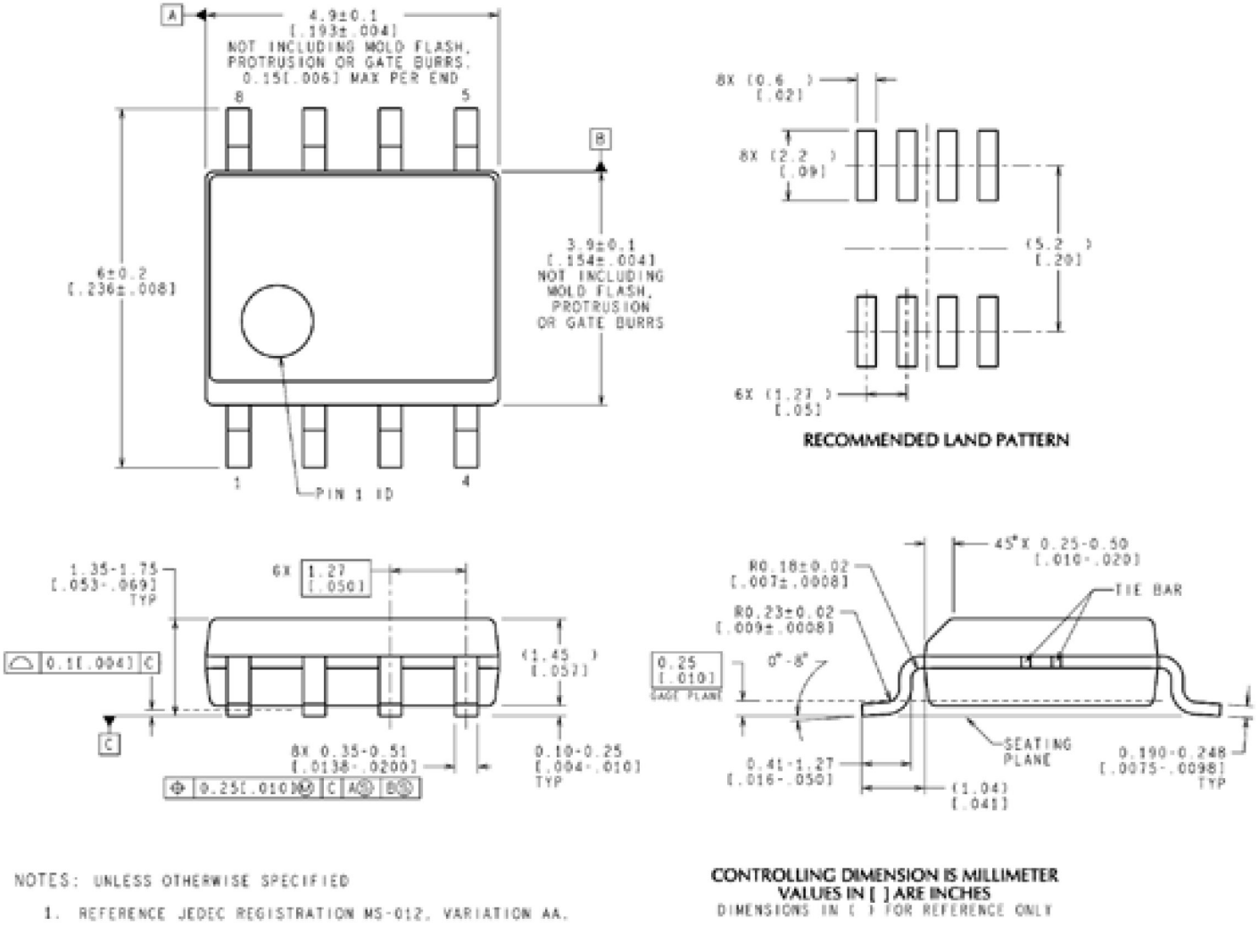


Figure 3. Deadtime Waveform Definitions

Package Dimensions (SOIC-8 N)

Please contact support@telefunkensemi.com for package availability.



NOTES: UNLESS OTHERWISE SPECIFIED

1. REFERENCE JEDEC REGISTRATION MS-012, VARIATION AA.

CONTROLLING DIMENSION IS MILLIMETER
VALUES IN [ ] ARE INCHES
DIMENSIONS IN ( ) FOR REFERENCE ONLY

Revision History

Rev.	Change	Owner	Date
1.0	First release, AI datasheet	Keith Spaulding	11/28/2022

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